

WHAT IS CLAIMED IS:

1. A memory device comprising:
a plurality of storage means for storing
information;
5 means for controlling said storage means;
means, having a resistance, for terminating
an electric signal; and
a pattern wiring for electrically connecting said
plurality of storage means, said controlling means and
10 said terminating means;

wherein said plurality of storage means, said
controlling means and said terminating means are
arranged on a board, and said pattern wiring being
located in a preset position on the board other than
15 a position in which said storage means is located.

2. The memory device according to claim 1,
wherein said pattern wiring is located on an insulating
portion of the board surface.

3. The memory device according to claim 2,
20 wherein said pattern wiring is arranged on a surface
layer of the board for transmitting the electric
signal, and the board being composed of multiple
layers.

4. The memory device according to claim 3,
25 wherein the electric signal is a signal transmitted
from said controlling means to said terminating means,
and an impedance of the electric signal having a preset

value.

5 5. The memory device according to claim 4,
further comprising means for generating a clock signal,
and supplying the clock signal to said storage means
connected to said terminating means.

6. The memory device according to claim 5,
wherein said plurality of storage means at least
including:

10 first storage means for receiving an output signal
from said controlling means, and said first storage
means being arranged on a front surface of the board,
and an input terminal of said first storage means
facing an output terminal of said controlling means;

15 second storage means for receiving an output
signal from said first storage means, and said second
storage means being arranged on a reverse surface of
the board; and

20 third storage means for receiving an output signal
from said second storage means, and an output terminal
of said third storage means facing an input terminal of
said terminating means;

25 wherein said pattern wiring is at least arranged
between said controlling means and said first storage
means, between said storage means, and between said
third storage means and said terminating means.

7. The memory device according to claim 5,
wherein said plurality of storage means at least

including:

first storage means for receiving an output signal
from said controlling means, and said first storage
means being arranged to face an output terminal of said
5 controlling means; and

second storage means for receiving an output
signal from said first storage means, said second
storage means being arranged to face an output terminal
of said first storage means, and an output terminal
10 of said second storage means being arranged to face
an input terminal of said terminating means;

wherein said pattern wiring is at least arranged
between said controlling means and said first storage
means, between said storage means, and between said
15 second storage means and said terminating means.

8. The memory device according to claim 7,
wherein an input terminal of said first storage means
is arranged to face the output terminal of said second
storage means;

20 the output terminal of said first storage means is
arranged to face an input terminal of said second
storage means; and

wherein said pattern wiring is arranged between
terminals of said first and second storage means.

25 9. The memory device according to claim 7,
wherein only the output terminal of said first storage
means and an input terminal of said second storage

means among the terminals of said first and second storage means are arranged to face each other, and said pattern wiring being arranged between said first and second storage means.

5 10. The memory device according to claim 7, wherein at least two of said plurality of storage means are individually provided in each of the front and reverse surfaces of the board, and said pattern wiring being connected between said storage means.

10 11. A socket mounting structure of a memory device comprising:

 a plurality of storage means for storing information;

 means for controlling said storage means;

15 means, having a resistance, for terminating an electric signal; and

 a pattern wiring for electrically connecting said plurality of storage means, said controlling means and said terminating means;

20 wherein said plurality of storage means, said controlling means and said terminating means are mounted on a board, and said pattern wiring being located in a preset position on the board other than a position in which said storage means is located.

25 12. The socket mounting structure of the memory device according to claim 11, wherein said pattern wiring is located on an insulating portion of the board

surface between said controlling means and said terminating means.

13. The socket mounting structure of the memory device according to claim 12, wherein the electric
5 signal is transmitted via a surface layer pattern of the board, and the board being composed of multiple layers.

14. The socket mounting structure of the memory device according to claim 13, wherein the electric
10 signal is a signal transmitted from said controlling means to said terminating means, and an impedance of the electric signal having a preset value.

15. The socket mounting structure of the memory device according to claim 14, further comprising means
15 for generating a clock signal, and supplying the clock signal to said storage means connected to said terminating means.

16. A mounting method of a memory device comprising:

20 mounting on a board a plurality of storage means for storing information;

mounting on the board a means for controlling said storage means;

25 mounting on the board a means, having a resistance, for terminating an electric signal; and

mounting on the board a pattern wiring for electrically connecting said plurality of storage

means, said controlling means and said terminating means;

5 wherein said pattern wiring is located in a preset position on the board other than a position in which said storage means is located.

10 17. The mounting method of the memory device according to claim 16, wherein said pattern wiring is mounted on an insulating portion of the board surface between said controlling means and said terminating means.

15 18. The mounting method of the memory device according to claim 17, wherein said pattern wiring is arranged on a surface layer of the board for transmitting the electric signal, and the board being composed of multiple layers.

20 19. The mounting method of the memory device according to claim 18, wherein the electric signal is transmitted from said controlling means to said terminating means, and an impedance of the electric signal being adjusted to have a preset value.

25 20. The mounting method of the memory device according to claim 19, further comprises mounting means for generating a clock signal, and supplying the clock signal to said storage means connected to said terminating means.